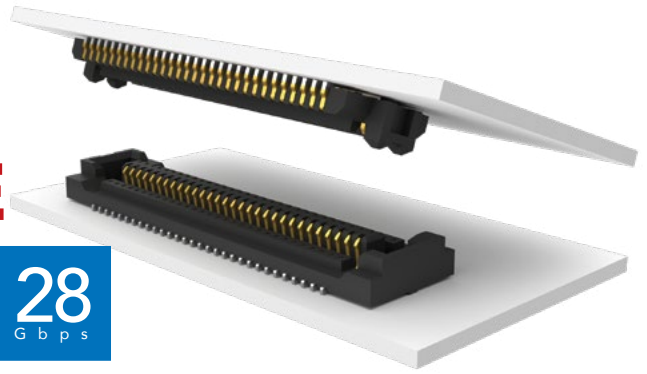


# ULTRA-LOW PROFILE HEADER & SOCKET

(0.50 mm) .0197" PITCH • SLH/TLH SERIES



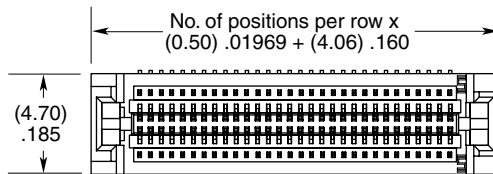
**SLH**  
Mates:  
TLH

**TLH**  
Mates:  
SLH

SLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030 (Per Row)	-1.50 =1.50 mm	-G = 10 μm (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad

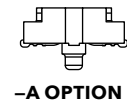
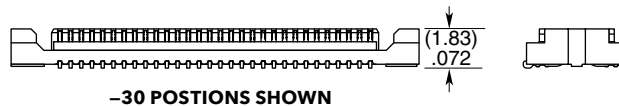
## SPECIFICATIONS

**Insulator Material:**  
Black Liquid Crystal Polymer  
**Contact Material:**  
Copper Alloy  
**Plating:**  
Au over 50 μm (1.27 μm) Ni  
**Current Rating:**  
2.1 A per pin  
(2 pins powered)  
**Operating Temp Range:**  
-55 °C to +125 °C



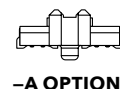
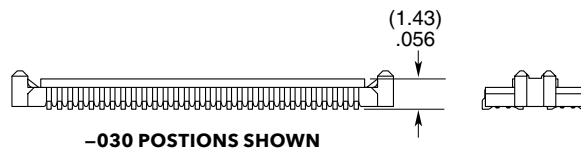
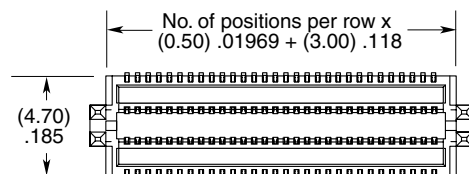
## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max  
**Board Stacking:**  
For applications requiring two  
or more connectors per board,  
contact [ipg@samtec.com](mailto:ipg@samtec.com)



-A OPTION

TLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030 (Per Row)	-0.50 =0.50 mm	-G = 10 μm (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad



-A OPTION

**Note:**  
Some lengths, styles and  
options are non-standard,  
non-returnable.